Band Switching Diodes

Panasonic

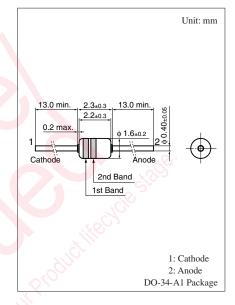
MA2C858 (MA858)

Silicon epitaxial planar type

For band switching

Features

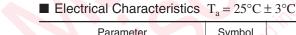
- Extra-small DHD envelope, allowing to insert into a 5 mm pitch hole
- \bullet Less voltage dependence of the diode capacitance $C_{\rm D}$
- \bullet Low forward dynamic resistance $r_{\rm f}$
- Optimum for a band switching of tuner



Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V _R	35	V
Forward current	I _F	100	mA
Operating ambient temperature *	T _{opr}	-25 to +85	°C
Storage temperature	T _{stg}	-55 to +100	°C

Note) *: Maximum ambient temperature during operation.



Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	$I_{\rm F} = 100 \ {\rm mA}$	8° ,	S	1.0	V
Reverse current *	IR	V _R = 33 V	and and a	0	100	nA
Diode capacitance	C _D	$V_R = 6 V, f = 1 MHz$	<i>.?</i> ~		1.2	pF
Forward dynamic resistance	r _f	$I_F = 2 \text{ mA}, f = 100 \text{ MHz}$			0.98	Ω

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz

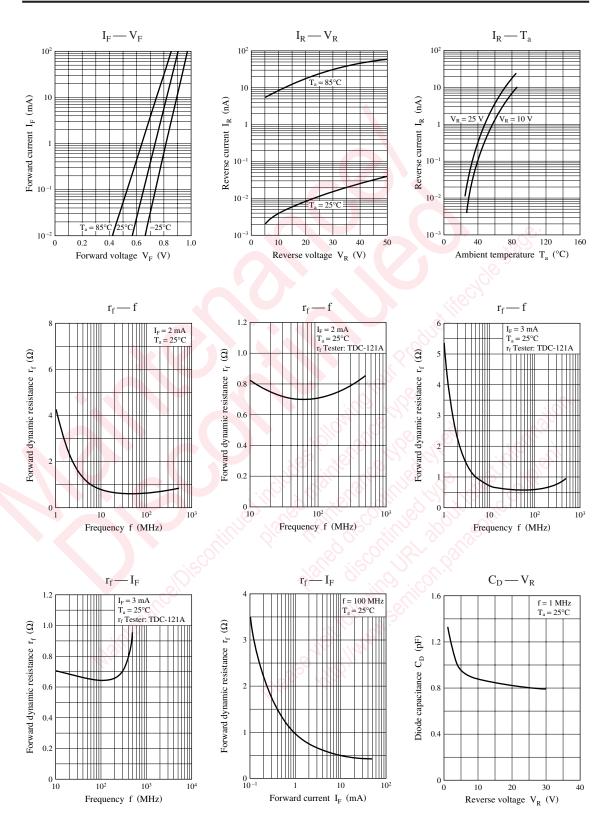
3. *: I_R should be measured under the condition of prevention the light.

Cathode Mark

Туре	e No.	MA2C858		
Color	1st Band	Yellow		
	2nd Band	Yellow		

Note) The part number in the parenthesis shows conventional part number.

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